



Silicon Motion, Inc.

SM3261 Test Program and ISP Release Note

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Release Date	ISP Version	ISP Check Sum	Test AP Version	Description
2012/09/18	120911-AB	SM3261ABISP.BIN SM3261ABISP-27nm.BIN SM3261ABISP-24nm.BIN SM3261ABISP-B74.BIN SM3261ABISP-L84.BIN SM3261ABISP-SA27nmMLC.BIN SM3261ABISP-SA21nmMLC.BIN SM3261ABISP-ISPT24nm.BIN SM3261ABISP-IPSPD24nm.BIN SM3261ABISP-ISPSA21nm.BIN SM3261ABISP-ISPT19nm.BIN SM3261ABISP-IPSPD19nm.BIN SM3261ABISP-IPSPD32nm.BIN 0082BFAE	V 2.3.92 v3 12/09/13 Build	<ol style="list-style-type: none"> 1. First SM3261AB MP tool / FW formal release 2. Support Samsung 21nm TLC ABG-C die / ACG-A die: K9ABGD8U0C / K9ACGD8U0A (x1 mode) 3. Support Samsung 21nm MLC GCG-A die: K9GCGD8U0A (x1 mode) 4. Support SanDisk 19nm TLC 128Gb: SDTNQCAMA-016G (x1 mode) 5. Support Toshiba 19nm TLC 128Gb: TC58TEG7T2JTA00 (x1 mode) 6. Support Micron 25nm MLC L74 DDR / TLC B74 SDR: MT29F64G08CBAAB / MT29F64G08EBAAA (x1 mode) 7. Support Micron 20nm MLC L84 SDR/DDR: MT29F64G08CBABA / MT29F64G08CBABB (x1 mode)
2012/10/11	121002-AB	SM3261ABPTEST.BIN 0x38D8BB SM3261AAISP.BIN 008373AC	V 2.3.95 v9 12/10/09 Build	<ol style="list-style-type: none"> 1. Update LED Flash status. 2. Update Samsung 21nm TLC K9ACGD8U0Ax1/x2 performance. 3. Support SanDisk /Toshiba 19nm 64Gb TLC: SDTNQCAMA-008G / TC58TEG6T2JTA00 4. Support SanDisk 19nm TLC SDR to DDR mode
2012/10/24	121022-AB	SM3261ABISP.BIN	V 2.3.98 v1	<ol style="list-style-type: none"> 1. Support SanDisk 19nm TLC, SDTNQCBMA-032G (1CE



		00834E89 SM3261ABISP-ISPSPD19nm.BIN 00834E89	12/10/23 Build	2Die) 2. Support Samsung 21nm TLC, K9BDGD8U0A (1CE 2Die) 3. Support Micron L73 (4K page), MT29F32G08CBACA 4. Support Intel L85 SDR, 29F16B08LCMF3 5. Support Toshiba 19nm MLC type B (16K 1Plane), TC58TEG6DCJTA00
2012/12/06	121130-AB	SM3261ABISP SM3261ABISP-B74	V2.5.03 v3 12/11/29 Build	1. Modify remapping table location 2. Support Toshiba 19nm MLC type C (16K 2Plane), TC58TEG6DDJTA00 3. Support Micron B74 1CE/2Die: MT29F256G08EJAAA 4. Support Micron L85: MT29F128G08CBCAB 5. Support Toshiba 19nm TLC 32Gb: TC58TEG5T2JTA0 6. Disable cache program for Samsung 21nm MLC GCG-A die
2013/01/03	121221-AB	SM3261ABPTEST.BIN SM3261ABISP.BIN SM3261ABISP-SA21nmML.BIN	V 2.5.06 v7 12/12/21 Build	1. Support Micron L74A 1CE/2Die: MT29F256G08CJAAB 2. Update PHY setting to improve compatibility. 3. Improve SPOR ability 4. Modify the Pretest flow for Hynix flash.
2013/01/24	130122-AB	SM3261ABISP.BIN	V 2.5.10 v6 13/01/17 Build	1. Modify Intel L84A initial original bad flow. 2. Improve IM L84 / L85 system block protection 3. Improve SPOR protection 4. Adjust driving current for Intel & Micron 20nm MLC L85A 1Ch 4Way 5. Fix LPM issue for USB3 suspend.



2013/03/18	130207-AB 130318-AB	SM3261ABISP.BIN SM3261ABPTEST-DA.BIN SM3261ABISP-ISPSPD19nm16K.BIN	V 2.5.15 v7 13/03/12 Build	<ol style="list-style-type: none"> 1. Support Toshiba 19nm MLC 8K 2Plane: TC58TEG6D2JTA00 2. Support SanDisk 19nm 64Gb MLC: SDTNQGAMA-008G with differential address 3. Support Micron 34nm MLC L63B: MT29F128G08CJABA 4. Improve SPOR 5. Revise PHY setting for 16K page flash. 6. Update L84 read-retry table 7. Improve Samsung 21nm read-retry flow 8. Fix L74 / B74 1CE/2Die initial fail bug.
2013/05/16	130503AB	SM3261ABISP.BIN	V 2.5.18 v1 13/04/25 Build	<ol style="list-style-type: none"> 1. Support Hynix 20nm UBG-C die / UCG-A die / UCG-B die: H27UBG8T2CTR / H27UCG8T2ATR / H27UCG8T2BTR / H27UCG8T2BYR 2. Support Toshiba 24nm SLC: TC58NVG5H2HTA00 3. Support SanDisk 19nm 64Gb DDR MLC:SDTNQGAMA-008GP 4. Support Micron L85 with 4way interleave: MT29F128G08CBCAB 5. Improve SPOR error handling 6. Enhance system block protection 7. New alignment to solve "Unallocated partition" issue in some specific capacity.
2013/06/18	130524AB	SM3261ABISP.BIN	V 2.5.22 v2 13/06/03	<ol style="list-style-type: none"> 1. Add Idle clean function to improve performance in dirty stage 2. Support Toshiba 32 / 24nm SLC: TC58NVG3S0FTA00 /



			Build	TH58NVG4S0FTA20 / TC58NVG5H2HTA00 / TH58NVG6H2HTA20 3. Support Micron 25nm SLC: MT29F128G08AJAAA 4. Enhance system block protection for Intel / Micron Flash 5. Support I/M 20nm MLC L85x4 with 4way interleave: 29F128G08CBCABx4
2013/07/30	130726AB	SM3261ABISP.BIN SM3261ABISP-IPSA19nm.BIN	V 2.5.25 v5 13/07/25 Build	1. Support Samsung 1xnm TLC, K9ADGD8U0M, K9ACGD8U0B 2. Support Spectek L85, FNNL85A71MDBABJ4-AL (8K 2Plane) 3. Support Micron L84C, 29F64G08CBEDB 4. Support Hynix 1xnm MLC, H27UCG8T2DTR 5. Support SanDisk 24nm MLC, SDTNPMAHEM-008G 6. Support Intel L74 2CE/8Die package, 29F64B08OCME1 7. Support Toshiba 32nm SLC, TH58TVG5S2FBA49BDJ 8. Support Toshiba 24nm SLC, TH58TEG6H2HBA4C, TH58TEG7H2HBA8C, TH58TEG8H2HBA89 9. Support Toshiba 19nm MLC, TC58TEG5DCJTA00, TH58TEG8DDJTA20 10. Support SanDisk 1ynm MLC, SDTNRGAMA-008G
2013/11/26	131119-AB	SM3261ABISP.BIN	V 2.5.29 v3 13/11/26 Build	1. Support Micron 16nm 128Gb MLC / L95B: 29F128G08CBECB 2. Support SanDisk 1ynm 64Gb MLC / TLC:



				SDTNRGAMA-008G / SDTNRCAMA-008G 3. Support Toshiba A19nm 64Gb MLC: TC58TEG6DDKTA00 4. Support Spectek L85: FBNL85A71KDBAAH6-AR 5. Adjust Intel & Micron 16K/512page flash (L8X/L9X) default setting capacity
2013/12/17	131214-AB	SM3261ABISP.BIN SM3261ABISP-L85	V 2.5.30 v2 13/12/12 Build	1. Improve L85 4way interleave SPOR handling. 2. Improve L85 pre-scan. 3. Support Micron L84D: 29F64G08CBCEB